

HLP LEAD BORATE

Application

This material is used to introduce lead into very low melting point sealing glasses such as solder glass for assembly of television tubes, display tubes and integrated circuit packages. It is available in either granulated or ground forms.

Physical Properties

Color.....White to pale yellow
 Form.....Granulated or ground
 Specific Gravity.....6.98 - 7.07
 Melting Point.....490 - 510°C. (914 - 950°)

Chemical Composition

PbO (litharge)	87.5 +/- 0.3%
B ₂ O ₃ (boric oxide)	12.5 +/- 0.3%
H ₂ O (water)	less than 0.03%

Trace Elements

Element	Maximum (%)
Fe ₂ O ₃	0.0100
ZnO	0.0008
Cu ₂ O	0.0006
Ag	0.0014
Bi ₂ O ₃	0.0100
As ₂ O ₅ , Sb ₂ O ₃ , SnO ₂	0.0009
Ni, Te, Th, Cd	0.0006
Co, Cr, Mn, Se	0.0002

Typical Screen Analysis (U.S. Standard Sieve)	Granular (%)	Ground (%)
greater than 4 mesh	0	0
between 4 – 8 mesh	0	0
between 8 – 10 mesh	0	0
between 10 – 20 mesh	42	0
between 20 – 40 mesh	40	0
between 40 – 80 mesh	13	0
between 80 – 100 mesh	2	0
between 100 – 200 mesh	1	0
Between 200 – 325 mesh	2	0.5
Less than 325 mesh	0	99.5

Packaging
50 lb. / 22.68 kg Paper bags
28-gallon steel drums (700 lbs. / 317.51 kg)

Note

This data sheet illustrates typical values for this product. If specific characteristics are required that are different from these values, please contact your area sales representative.



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